



Material Content Data Sheet



Sales Product Name				IPD60R180C7		Issued		18. April 2016	
MA#				MA001489036					
Package				PG-TO252-3-313		Weight*		319.48 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.951	1.24	1.24	12367	12367	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		461		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
	non noble metal	copper	7440-50-8	147.096	46.05	46.11	460418	461017	
wire	non noble metal	aluminium	7429-90-5	1.909	0.60	0.60	5976	5976	
encapsulation	organic material	carbon black	1333-86-4	1.386	0.43		4338		
	plastics	epoxy resin	-	24.253	7.59		75913		
	inorganic material	silicondioxide	60676-86-0	112.949	35.35	43.37	353537	433788	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11707	11707	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4446	4457	
solder	noble metal	silver	7440-22-4	0.085	0.03		265		
	non noble metal	tin	7440-31-5	0.068	0.02		212		
	non noble metal	lead	7439-92-1	3.229	1.01	1.06	10107	10584	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	60026	60104	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com